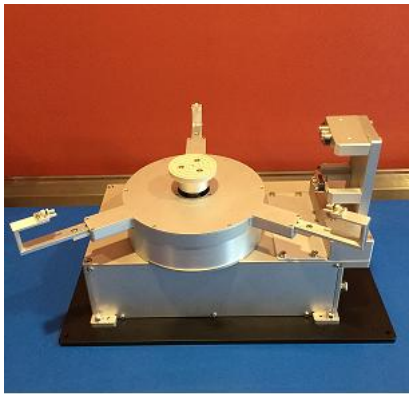


DSVC 300/200 ALIGNER

DSVC aligner has double slots, vacuum chuck, and grippers. The vacuum chuck is to spin the wafer. The grippers are to center and lower the wafer from upper slot on to the chuck. Robot swaps unprocessed and processed wafers at DSVC aligner to save wafer handling steps.

The grippers, with patented soft touch technology, applies constantly monitored force, no stress to the wafer.

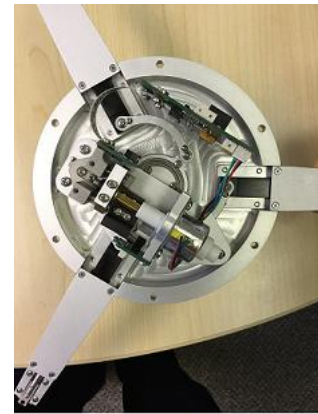
DSVC 300 has similar footprint and height that it can directly replace EQUIP/PRI PRE aligners.



DSVC 300



DSVC 300 w/ Options

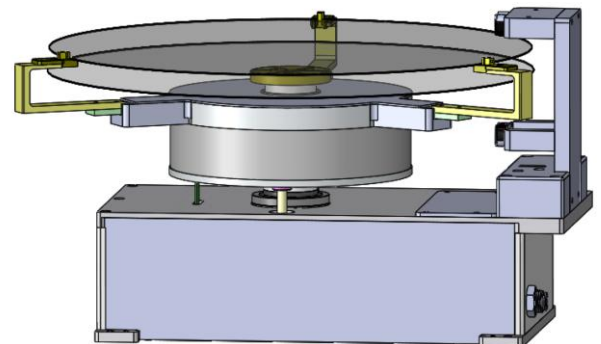


Soft Touch Gripper

DSVC 200 is the 200mm version of the DSVC ALIGNERS. Both DSVC 300mm and 200mm share same mechanical base. They are interchangeable through a conversion kit.

Specifications:

- 1) Dimensions (mm): 173 x 249 x 159 (h)
- 2) Weight: 6.0kg
- 3) Vacuum, 250 Torr max
- 4) Buffer Station: YES
- 5) Wafer Diameters: 200mm and 300mm
- 6) Wafer Thickness (mm): > 0.2
- 7) Notch Repeatability (degree): 0.01
- 8) Z Repeatability (mm): 0.05
- 9) Typical Align Time (sec): 4.5



OCR on ALIGNERS

Optionally, Cognex Insight 1741 OCR is integrated on the DSVC 300, which further saved wafer handling steps.

The Cognex 1740 series are capable of reading semi font, OCR-A, IBM, T7, BC412, and IBM412.



DSVC 300 w/ Options

Particle Cleaning Air Blower

A three nozzle air blower can also be attached to the DSVC 300 ALIGNER. The blowers help removing particles from the chamber.

Contact Us

USA:

Open Vision Technology, LLC.

Email: gen@openvisiontech.com

Tel: +1 339-293-2151

Web: www.openvisiontech.com